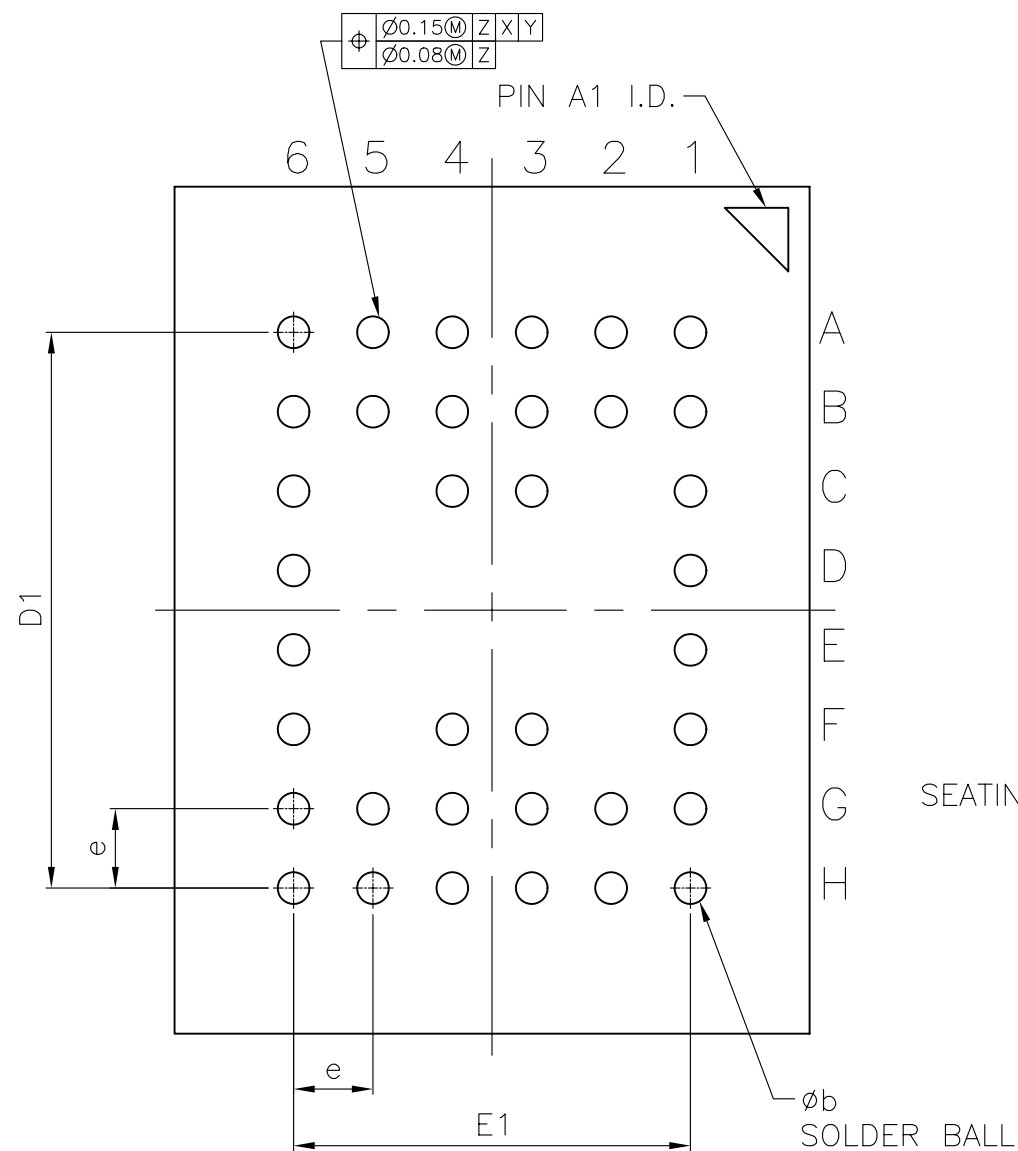
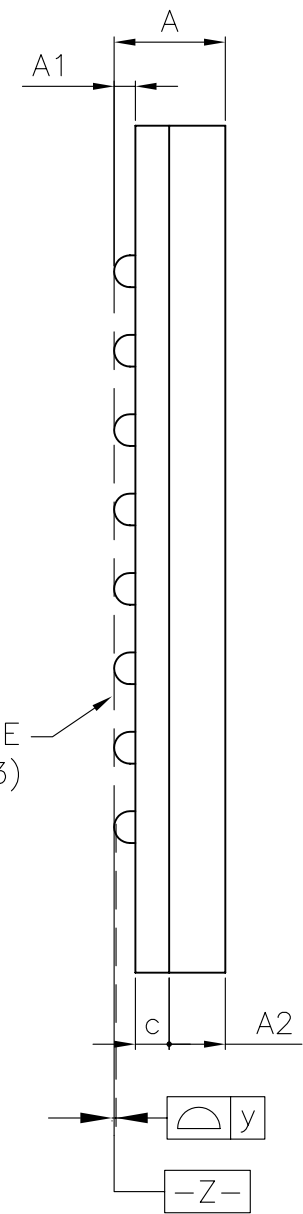
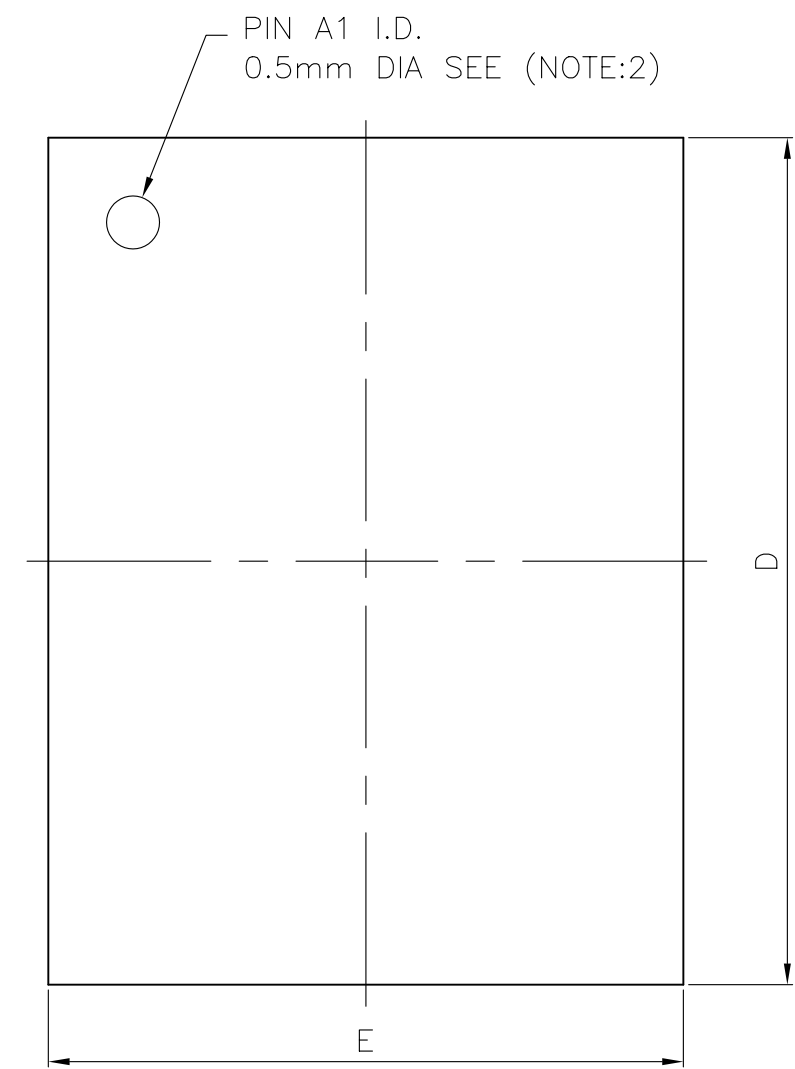


BOTTOM SIDE BOTTOM VIEW



TOP SIDE TOP VIEW



- NOTE :
1. ALL DIMENSION ARE IN MILLIMETERS.
 2. PIN A1 ID. TO BE MARKED BY INK OR LASER.
 3. PRIMARY DATUM $[Z-]$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 4. "e" REPRESENTS THE MAXIMUM SOLDER BALL GRID PITCH.
 5. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL PITCH. PARALLEL TO PRIMARY DATUM $[Z-]$.

SYMBOLS	DIMENSIONS IN MILLIMETERS		
	MIN	NOM	MAX
A	1.00	1.10	1.20
A1	0.15	0.20	0.25
A2	0.52	0.53	0.54
ϕb	0.25	0.30	0.40
c	—	0.32	—
D	7.90	8.00	8.10
D1	—	5.25	—
E	5.90	6.00	6.10
E1	—	3.75	—
e	—	0.80	—
y	—	—	0.10

CUSTOMER :		LINGSEN 5-1 NAN 2ND ROAD T.E.P.Z PRECISION IND., LTD. TAICHUNG., TAIWAN. R. O. C	
APPROVED BY	DATE	TITLE:	
DRAW BY: <i>Sandy Sue</i>	08/18/06	MINI BGA 36L(6x8mm) PACKAGE OUTLINE DRAWING	
CHECK BY: <i>S. S. Lin</i>	08/18/06	DWG. NO.	REV.
APPROVAL: <i>Jack Tu</i>	08/21/06	PO-MBGA-007	2
APPROVAL: <i>Jack Tu</i>	08/21/06	UNIT :	SCALE :
		mm	14/1
		SHEET 1 OF 1	